

iMiD 2019

August 27 - 30, 2019 / HICO, Gyeongju, Korea



Company Name	DISCO Corporation	Company Logo
Address	(Korea Local Office) 3F, DHK Solution Bldg., 28, Pangyo-ro 255beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea 13486 (Japan Main Office) 13-11 Omori-Kita 2-chome, Ota-ku, Tokyo 143-8580 Japan	
President	Kazuma Sekiya	
Website	http://www.disco.co.jp	
E-Mail	dhkas@disco.co.jp(Local)	
Telephone	82-31-8038-8250(Local)	
Fax	82-31-8038-8251(Local)	
Company Introduction	<div><div>1.</div><div>Manufacture and sale of precision cutting, grinding and polishing machines</div></div> <div><div>2.</div><div>Maintenance of precision cutting, grinding and polishing machines</div></div> <div><div>3.</div><div>Training in the operation and maintenance of precision cutting, grinding and polishing machines</div></div> <div><div>4.</div><div>Disassembly and recycling of precision cutting, grinding and polishing machines</div></div> <div><div>5.</div><div>Lease of precision machines and sale and purchase of used machines</div></div> <div><div>6.</div><div>Manufacture and sale of precision diamond abrasive tools</div></div> <div><div>7.</div><div>For-fee processing</div></div>	
Exhibit Description	<div>• LASER Lift OFF (LLO) 가공설명</div> <div>• LLO Process의 소개</div> <div>• Sapphire・Glass향 LASER 가공소개 (LEAF Process)</div>	
Exhibit Product	<div>• LLO Process Sample for Micro LED</div> <div>• LLO Process Sample for V-LED</div> <div>• LEAF Process Sample</div>	